

# amasan Thermal Compound T12

**Fill-expedient which carries off heat between the contact surfaces of the semiconductors and radiators**

amasan Thermal Compound T12 is a chemically neutral, white, non-transparent silicon paste with good heat conductivity and heat resistance until 200°C.

amasan Thermal Compound T12 does not dry up, it is not getting hard and is not melting. It is consistency stable at high and low temperatures as well as in storage.

amasan Thermal Compound T12 can be used as fill-expedient which carries off heat between the contact surfaces of the semiconductors and radiators. At the assembly of semiconductors, like diodes and transistors, and appliance of amasan Thermal Compound T12 the heat isolating air will be replaced by the silicon paste. The heat transition from mounting component to radiator will consequently be improved and through this the efficiency of the mounting component will be increased substantially.

amasan Thermal Compound T12 should be applied evenly and thin with a brush or a spatula on both contact surfaces. The residues should be removed.

amasan Thermal Compound T12 is available in tubes with syringe containing 5 g, 35 g and 100 g as well as in tins containing 250 g, 500 g and 1.000 g.

## Specification:

structure:	based on silicon
colour:	white, non-transparent
consistency:	like vaseline
density at 25°C:	2,3
temperature range:	-30°C until +200°C
bleeding after 24 hrs at 200°C:	0,4 %
fleeing after 24 hrs at 200°C:	1,0 %
heat conductivity W/mk:	0,90



OEEG